

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Signey et al.

Serial No: TBD

Filed: 10/11/01

For: METHOD AND SYSTEM FOR CUTTING INTEGRATED CIRCUIT
PACKAGES

J. Nelson
#2/IDS
1-8-02
Docket No.: TI-27954

Examiner: TBD

Art Unit: TBD

JC986 U.S. PTO
001975219
10/11/01

INFORMATION DISCLOSURE STATEMENT

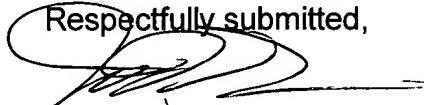
Assistant Commissioner for Patents

Washington, DC 20231

Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. Copies of the listed references are enclosed.

Respectfully submitted,


Jacqueline J. Garner
Attorney for Applicants
Reg. No. 36,144

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972)271-1176 or (972) 917-5643
(972)917-4418 Fax